



Material Content Data Sheet



Sales Product Name		BTT6030-1EKA		Issued		29. August 2013		
MA#		MA001134406						
Package		PG-DSO-14-47		Weight*		150.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.468	1.64	1.64	16406	16406
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		460	
	non noble metal	iron	7439-89-6	1.383	0.92		9198	
wire	non noble metal	copper	7440-50-8	56.175	37.35	38.33	373487	383260
	non noble metal	copper	7440-50-8	0.624	0.41	0.41	4146	4146
	encapsulation	organic material	carbon black	1333-86-4	0.170	0.11		1129
plastics	plastics	epoxy resin	-	7.813	5.19		51944	
	inorganic material	silicondioxide	60676-86-0	76.939	51.17	56.47	511541	564614
leadfinish	non noble metal	tin	7440-31-5	2.472	1.64	1.64	16433	16433
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9776	9776
glue	plastics	epoxy resin	-	0.141	0.09		939	
	noble metal	silver	7440-22-4	0.666	0.44	0.53	4426	5365
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com